

LNA-IC for 1.5GHz Band Applications

FEATURES

Low voltage operation +2.85 V typ.
 Low current consumption 9.5 mA typ.
 High gain 19 dB typ. fRX = 1 575 MHz
 Low noise figure 0.86 dB typ. fRX = 1 575 MHz
 Low distortion +4 dBm typ. fRX = 1 575 MHz
 (IIP3 +10 MHz offset)

 Small package5 pin Plastic Small Surface Mount Package (SMINI Type)

DESCRIPTION

AN26014A is LNA-IC for 1.5 GHz Band Applications. Realizing high performance by using 0.18 μ m SiGeC Bi-CMOS process(f_T = 90 GHz, f_{max} = 140 GHz).

Sleep mode is available, controlled by integrated CMOS logic circuit.

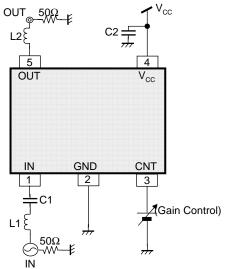
Achieving miniaturization by using small size package.

APPLICATIONS

•GPS

SIMPLIFIED APPLICATION

TOP VIEW



Components	Size	Value	Part Number	Vendor
L1	0603	3.0 nH	LQP03T3N0B04	Murata
L2	0603	5.6 nH	LQP03T5N6H04	Murata
C1	0603	1 000 pF	GRM033B11C102KD01	Murata
C2	0603	0.1 uF	GRM33B30J104KE18	Murata

Notes) This application circuit is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit	Note
Supply voltage	V _{CC}	3.6	V	*1
Supply current	I _{cc}	18	mA	_
Operating ambient temperature	T _{opr}	-20 to 70	°C	*2
Operating junction temperature	T _j	-40 to +125	°C	*2
Storage temperature	T _{stg}	-55 to +125	°C	*2
	IN (Pin No.1)	_	V	*3
Input Voltage Range	CNT (Pin No.3)	-0.3 to (V _{CC} + 0.3)	V	*4
	OUT (Pin No.5)	-0.3 to (V _{CC} + 0.3)	V	*4
FOD	HBM (Human Body Model)	2	kV	_
ESD	MM (Machine Model)	200	V	_

Notes). This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating. This rating is the maximum rating and device operating at this range is not guaranteeable as it is higher than our stated recommended operating range.

When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

POWER DISSIPATION RATING

PACKAGE	θ _{JA}	PD (Ta=25 °C)	PD (Ta=70 °C)
SSMINI-5DC	833.3°C/W	0.12W	0.06W

Note). For the actual usage, please refer to the PD-Ta characteristics diagram in the package specification, supply voltage, load and ambient temperature conditions to ensure that there is enough margin follow the power and the thermal design does not exceed the allowable value.



CAUTION

Although this has limited built-in ESD protection circuit, but permanent damage may occur on it. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage range	V _{cc}	2.70	2.85	3.0	V	*1

Note) *1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

^{*1:}The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

^{*2:}Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for Ta = 25°C.

^{*3:}RF signal input pin. Do not apply DC current.

^{*4:(}Vcc + 0.3) V must not be exceeded 3.6 V



ELECRTRICAL CHARACTERISTICS

Note) Vcc = 2.85 V, Ta = $25^{\circ}\text{C}\pm2^{\circ}\text{C}$ unless otherwise specified.

	Parameter		Symbol Conditions		Limits			Note
	Farameter	Symbol	Conditions	Min	Тур	Max	Unit	Note
DC el	ectrical characteristics							
	Supply current	IccH	Vcc current at Active mode No input signal	_	9.5	13.0	mA	_
	Sleep current	IccS	Vcc current at Sleep mode No input signal	_	1	10	μА	_
	CNT current (On)		CNT current at Active mode No input signal	_	5	35	μА	
	CNT current (Sleep)	IcntL	CNT current at Sleep mode No input signal	_	0.5	10	μА	_
	CNT voltage (On)	VIH		2.57	2.85	_	V	_
	CNT voltage (Sleep)	VIL		_	0	0.37	V	_



ELECRTRICAL CHARACTERISTICS (continued)

Note) Vcc = 2.85 V, $Ta = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$, fRX = 1.575 MHz, PRX = -30 dBm, CW unless otherwise specified.

	Parameter	Symbol	Conditions	Limits			Unit	Note
	raiailletei	Symbol	Conditions	Min	Тур	Max	Offic	NOTE
LNA A	C electrical characteristic	S						
	Power Gain	PGS	f = 1 575 MHz, PRX = - 30 dBm	16.7	19.0	20.7	dB	_
	IIP3 +10 MHz offset	IIP31S	f1 = fRX + 10 MHz f2 = fRX + 20 MHz Input 2 signals (f1, f2)	0	4.0	_	dBm	_
	IIP3 -10 MHz offset	IIP32S	f1 = fRX - 10 MHz f2 = fRX - 20 MHz Input 2 signals (f1, f2)	0	4.0	_	dBm	_



APPLICATION INFORMATION REFERENCE VALUES FOR DESIGN

Note) Vcc = 2.85 V

All characteristics are specified under Ta = 25°C $\pm 2^{\circ}\text{C},~\text{fRX}$ = 1575 MHz , PRX = -30 dBm , CW

	Demonstra	Ob.al		Refer	ence va	alues	11!1	Note
	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	Note
LNA	AC electrical characteristics							
	Noise Figure	NF	f = fRX	_	1.0	1.4	dB	*1 , *2
	Reverse Isolation	ISO	f = fRX	_	-32	-21	dB	*1
	Input Return Loss	S11	f = fRX	7	9.5	_	dB	*1
	Output Return Loss	S22	f = fRX	10	13	_	dB	*1

Note) *1 : Checked by design, not production tested.

*2 : Connector & substrate loss (0.14 dB) included.



APPLICATION INFORMATION (continued) REFERENCE VALUES FOR DESIGN (continued)

Notes) Vcc = 2.7 V to 3.0 V

All characteristics are specified under Ta = -20 °C to 70 °C, fRX = 1 575 MHz, PRX = -30 dBm, CW

	Parameter		Symbol Conditions		Reference values			Note
			Conditions	Min	Тур	Max	Unit	Note
DC ele	ectrical characteristics							
	Supply current	IccHT	Vcc current No input signal	_	9.5	14.0	mA	*1
	Sleep current	IccST	Vcc current at Sleep mode No input signal	_	1	12	μА	*1
	CNT current (On) IcntHT		CNT current at Active mode No input signal	_	5	40	μΑ	*1
	CNT current (Sleep)	IcntLT	CNT current at Sleep mode No input signal		0.5	12	μΑ	*1

Note) *1 : Checked by design, not production tested.



APPLICATION INFORMATION (continued) REFERENCE VALUES FOR DESIGN (continued)

Notes) Vcc = 2.7 V to 3.0 V

All characteristics are specified under Ta = -20 °C to 70 °C, fRX = 1 575 MHz, PRX = -30 dBm, CW

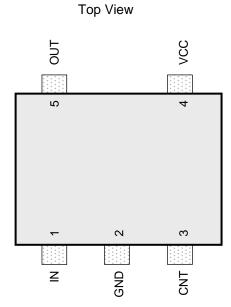
	Parameter	Cumbal	Conditions	Reference Values			Unit	Note
	Parameter	Symbol	Conditions	Min	Тур	Max	Unit	Note
LNA A	AC electrical characteristics							
F	Power Gain	GT	f = fRX	16.0	19.0	21.5	dB	*1
1	Noise Figure	NFT	f = fRX	_	1.0	1.6	dB	*1 , *2
ı	IIP3 +10 MHz offset	IIP31T	f1 = fRX + 10 MHz f2 = fRX + 20 MHz Input 2 signals (f1, f2)	- 1.0	4.0	_	dBm	*1
I	IIP3 -10 MHz offset	IIP32T	f1 = fRX - 10 MHz f2 = fRX - 20 MHz Input 2 signals (f1, f2)	- 1.0	4.0	_	dBm	*1

Note) *1 : Checked by design, not production tested.

*2 : Connector & substrate loss (0.14 dB) included.



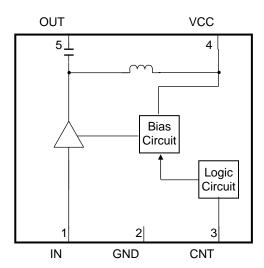
PIN CONFIGURATION



PIN FUNCTIONS

Pin No.	Pin name	Туре	Description			
1	IN	Input	RF Input			
2	GND	Ground	ND			
3	CNT	Input	CNT (Sleep mode) L: Sleep Mode H: On Mode			
4	VCC	Power Supply	V _{cc}			
5	OUT	Output	RF Output			

FUNCTIONAL BLOCK DIAGRAM



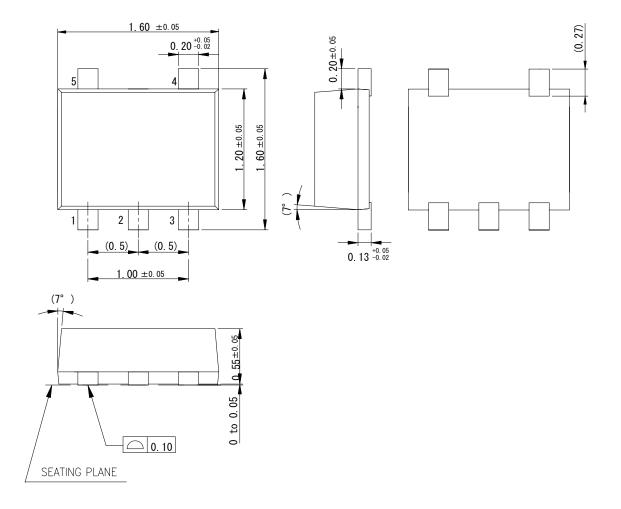
Notes) • This block diagram is for explaining functions. Part of the block diagram may be omitted, or it may be simplified.



PACKAGE INFORMATION (Reference Data)

Package Code:SSMINI-5DC

Unit:mm



Body Material : Br / Sb Free Epoxy Resin

Lead Material : Cu Alloy

Lead Finish Method: SnBi Plating



IMPORTANT NOTICE

- 1.The products and product specifications described in this book are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- 2. When using the LSI for new models, verify the safety including the long-term reliability for each product.
- 3. When the application system is designed by using this LSI, be sure to confirm notes in this book. Be sure to read the notes to descriptions and the usage notes in the book.
- 4.The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products. No license is granted in and to any intellectual property right or other right owned by Panasonic Corporation or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information de-scribed in this book.
- 5. This book may be not reprinted or reproduced whether wholly or partially, without the prior written permission of our company.
- 6. This LSI is intended to be used for general electronic equipment [1.5 GHz Band Applications].

Consult our sales staff in advance for information on the following applications: Special applications in which exceptional quality and reliability are required, or if the failure or malfunction of this LSI may directly jeopardize life or harm the human body.

Any applications other than the standard applications intended.

- (1) Space appliance (such as artificial satellite, and rocket)
- (2) Traffic control equipment (such as for automobile, airplane, train, and ship)
- (3) Medical equipment for life support
- (4) Submarine transponder
- (5) Control equipment for power plant
- (6) Disaster prevention and security device
- (7) Weapon
- (8) Others: Applications of which reliability equivalent to (1) to (7) is required

It is to be understood that our company shall not be held responsible for any damage incurred as a result of or in connection with your using the LSI described in this book for any special application, unless our company agrees to your using the LSI in this book for any special application.

- 7. This LSI is neither designed nor intended for use in automotive applications or environments unless the specific product is designated by our company as compliant with the ISO/TS 16949 requirements.
 - Our company shall not be held responsible for any damage incurred by you or any third party as a result of or in connection with your using the LSI in automotive application, unless our company agrees to your using the LSI in this book for such application.
- 8.If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
- 9. Please use this product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Our company shall not be held responsible for any damage incurred as a result of your using the LSI not complying with the applicable laws and regulations.



USAGE NOTES

- 1. When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
 - Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- 2. Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
- 3. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might smoke or ignite.
- 4. Pay attention in the PCB (printed-circuit-board) pattern layout in order to prevent damage due to short circuit between pins. In addition, refer to the Pin Description for the pin configuration.
- 5. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
- 6. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short).

And, safety measures such as an installation of fuses are recommended because the extent of the abovementioned damage and smoke emission will depend on the current capability of the power supply.

Request for your special attention and precautions in using the technical information and semiconductors described in this book

- (1) If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
- (2) The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products. No license is granted in and to any intellectual property right or other right owned by Panasonic Corporation or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information described in this book.
- (3) The products described in this book are intended to be used for general applications (such as office equipment, communications equipment, measuring instruments and household appliances), or for specific applications as expressly stated in this book. Consult our sales staff in advance for information on the following applications:
 - Special applications (such as for airplanes, aerospace, automotive equipment, traffic signaling equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
 - It is to be understood that our company shall not be held responsible for any damage incurred as a result of or in connection with your using the products described in this book for any special application, unless our company agrees to your using the products in this book for any special application.
- (4) The products and product specifications described in this book are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
 - Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
- (7) This book may be not reprinted or reproduced whether wholly or partially, without the prior written permission of our company.

20100202

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for RF Amplifier category:

Click to view products by Panasonic manufacturer:

Other Similar products are found below:

A82-1 BGA622H6820XTSA1 BGA 728L7 E6327 BGB719N7ESDE6327XTMA1 HMC397-SX HMC405 HMC561-SX HMC8120-SX HMC8121-SX HMC-ALH382-SX HMC-ALH476-SX SE2433T-R SMA3101-TL-E SMA39 A66-1 A66-3 A67-1 LX5535LQ LX5540LL MAAM02350 HMC3653LP3BETR HMC549MS8GETR HMC-ALH435-SX SMA101 SMA32 SMA411 SMA531 SST12LP17E-XX8E SST12LP19E-QX6E WPM0510A HMC5929LS6TR HMC5879LS7TR HMC1126 HMC1087F10 HMC1086 HMC1016 SMA1212 MAX2689EWS+T MAAMSS0041TR MAAM37000-A1G LTC6430AIUF-15#PBF CHA5115-QDG SMA70-2 SMA4011 A231 HMC-AUH232 LX5511LQ LX5511LQ-TR HMC7441-SX HMC-ALH310